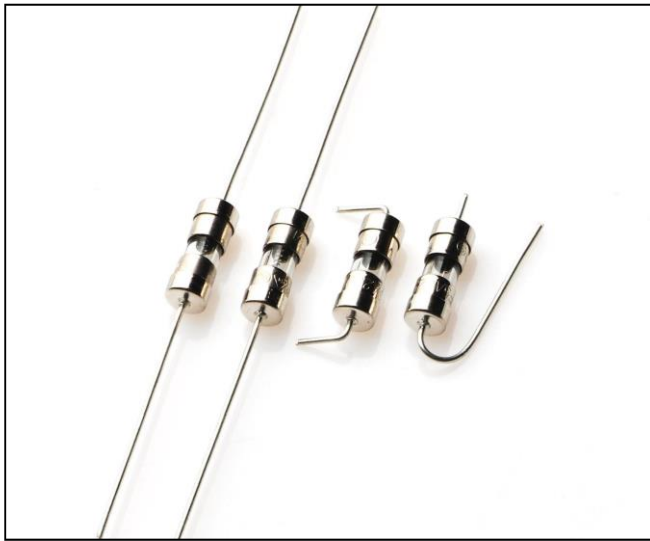


# Type TDP

## Time-Lag Micro Fuses Series



### Description

TDP, Time-lag Type, 250V rated designed in accordance to IEC 60127.3, GB/T9364.3, UL 248-14.

### Features

- Lead-free
- Reduced PCB space requirements
- Direct solderable or plug-in versions
- Low internal resistance
- Vibration resistant
- Internationally approved
- Shock safe casing
- Halogen free

### Applications

- Power supplies
- Consumer Electronics
- Adapter
- Battery Chargers
- Industrial Controllers

### Agency Approvals.

Safety Agency	Agency File Number	Ampere Range Volt@I.R.ABILITY
	R 50510065	250mA~3.15A 35A@250V AC 4A~10A 10In@250V AC
	2020970207000097	250mA~3.15A 35A@250V AC 4A~6.3A 10In@250V AC
	SU05050-15004(≤800mA) SU05050-15005(3.15A~6.3A) SU05050-15006(1A~2.5A)	250mA~3.15A 35A@250V AC 4A~6.3A 10In@250V AC
	E485357	250 mA~15A 50A@125V AC 250mA~15A 50A@250V AC

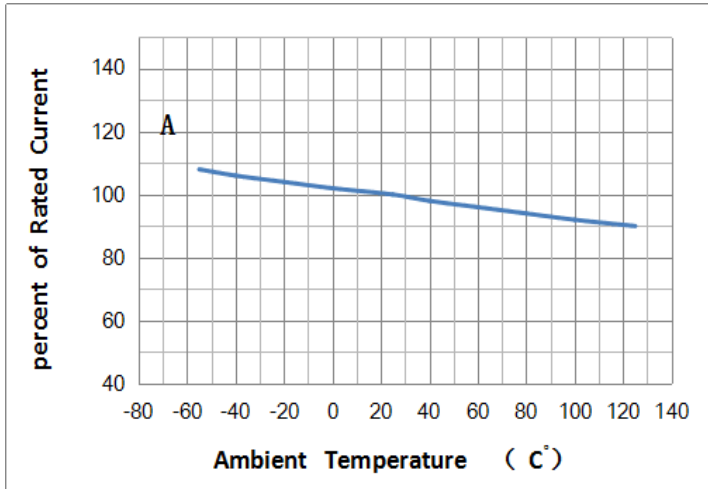
### Electrical Characteristics for Series

% of Ampere Rating	Opening Time
150%	1 Hour, Min
210%	2min,Max
275%	400ms Min,10s Max
400%	150ms Min,3s Max
1000%	20ms Min,150ms Max

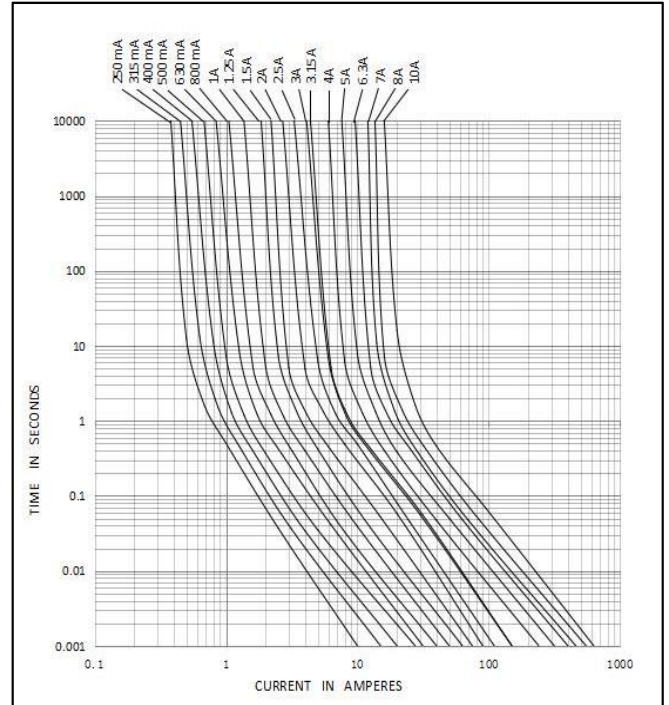
### Electrical Characteristic Specifications by Item

Catalog Number	Rated Current	Voltage Rating	Breaking Capacity	Melting Integral 10In min(A2S)	Agency Approvals			
					TUV	CCC	cULus	KC
TDP0250	250mA	125V AC 250V AC	50A@125V AC 50A@250V AC	0.300	●	●	●	●
TDP0315	315mA			0.556	●	●	●	●
TDP0400	400mA			0.928	●	●	●	●
TDP0500	500mA			1.125	●	●	●	●
TDP0630	630mA			2.183	●	●	●	●
TDP0800	800mA			3.584	●	●	●	●
TDP1100	1A			4.400	●	●	●	●
TDP1125	1.25A			7.031	●	●	●	●
TDP1160	1.6A			11.776	●	●	●	●
TDP1200	2A			23.200	●	●	●	●
TDP1250	2.5A			29.375	●	●	●	●
TDP1300	3A			50.605			●	
TDP1315	3.15A			50.605	●	●	●	●
TDP1400	4A			76.800	●	●	●	●
TDP1500	5A			132.500	●	●	●	●
TDP1630	6.3A			218.295	●	●	●	●
TDP1700	7A			220.000			●	
TDP1800	8A			276.000	●		●	
TDP2100	10A			369.000	●		●	

### Temperature Re-rating Curve

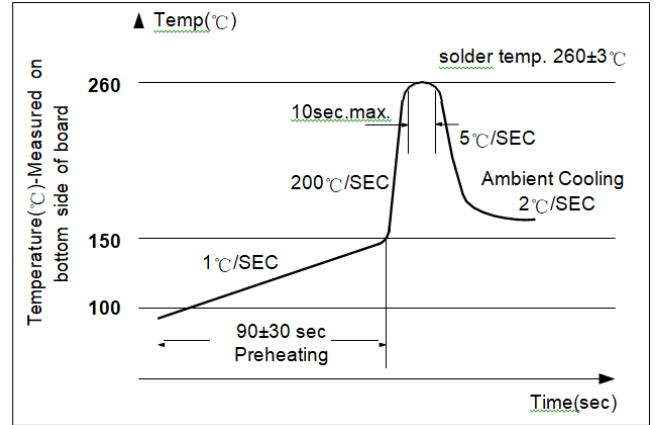


### Average Time Current Curves



### Soldering Parameters-Wave Soldering

Lead-Free Wave Soldering Profile	
Wave Soldering Parameter	
Average ramp-up rate	200°C/second
Heating rate during preheat	Typical 1-2°C/second Max 4°C/second
Final preheat temperature	Within 125°C of Soldering temperature
Peak temperature	260°C
Time within +0/-5°C of actual peak temperature	10 seconds
Ramp-down Rate	5°C/second max



# Type TDP

## Time-Lag Micro Fuses Series

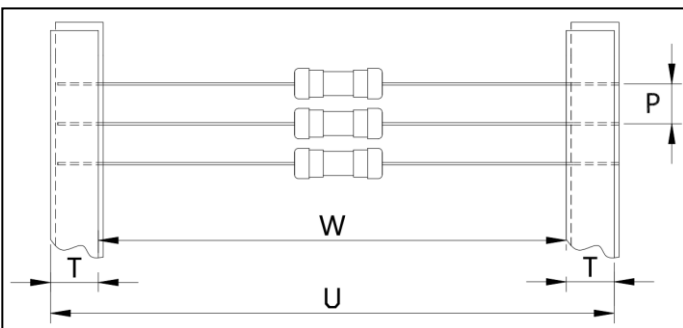
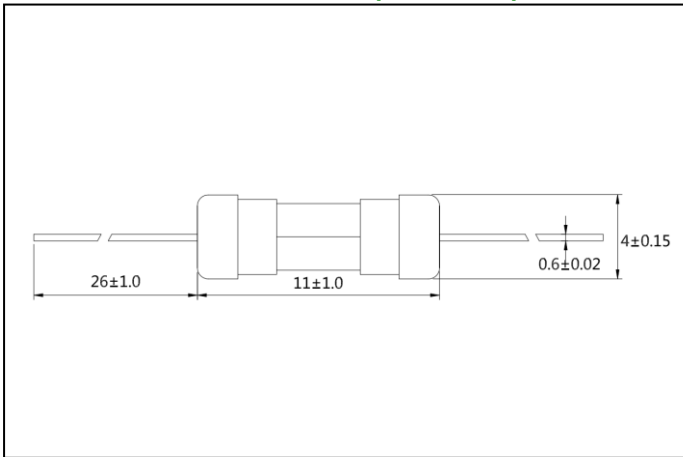


### Product Characteristics

Materials	Glass Body Nickel Plated Brass Caps Lead Wire :Diameter 0.8mm、0.6mm
Lead Pull Strength	10 N(IEC 60068-2-21)
Soldering Parameters	260°C, ≤10 sec.(wave) 350°C, ≤3 sec.(soldering iron)
Soldering Heat Resistance	260°C, 10 sec.(IEC 60068-2-20) 350°C, ≤3 sec.(soldering iron)

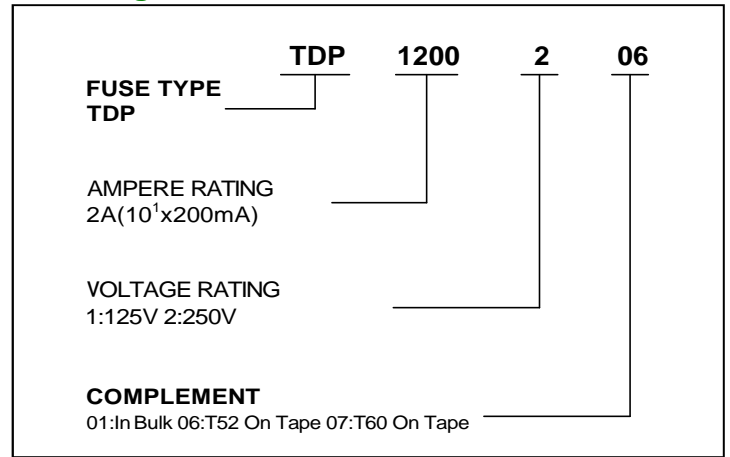
Operating Temperature	-55°C to +125°C(consider de-rating)
Climatic Category	-40°C to +85°C/21 days (EN 60068-1, -2-1, -2-2, -2-78)
Stock Condition	+10°C to +60°C Relative humidity ≤75% yearly Average, without dew, maximum Value for 30 days-95%
Vibration Resistance	24 cycles at 15 min. each (EN 60068-2-6) 10-60 Hz at 0.75 mm amplitude 60-2000 Hz at 10 g acceleration

### Mechanical Dimensions(Unit:mm)



编带标准	W	U	T	P
T52	52±1.5	65±1.5	6±0.2	5±0.05
T60	60±1.5	73.5±1.5	6±0.2	5±0.05

### Ordering Information



### Packaging

Packaging Option	Packaging Specification	Quantity
On Tape	N / A	1000pcs & 1500pcs
In Bulk	N / A	300pcs